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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	352
Number of Logic Elements/Cells	3168
Total RAM Bits	221184
Number of I/O	140
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp2-5fgg256i

The Trace port provides instruction execution trace information to an external trace tool. The PPC405 core is capable of back trace and forward trace. Back trace is the tracing of instructions prior to a debug event while forward trace is the tracing of instructions after a debug event.

The processor JTAG port and the FPGA JTAG port can be accessed independently, or the two can be programmatically linked together and accessed via the dedicated FPGA JTAG pins.

For detailed information on the PPC405 JTAG interface, please refer to the "JTAG Interface" section of the **PowerPC 405 Processor Block Reference Guide**

CoreConnect™ Bus Architecture

The Processor Block is compatible with the CoreConnect™ bus architecture. Any CoreConnect compliant cores including Xilinx soft IP can integrate with the Processor Block through this high-performance bus architecture implemented on FPGA fabric.

The CoreConnect architecture provides three buses for interconnecting Processor Blocks, Xilinx soft IP, third party IP, and custom logic, as shown in Figure 15:

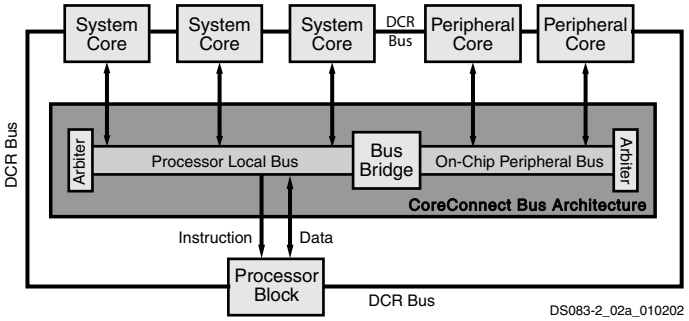

Figure 15: **CoreConnect Block Diagram**

- Processor Local Bus (PLB)
- On-Chip Peripheral Bus (OPB)
- Device Control Register (DCR) bus

High-performance peripherals connect to the high-bandwidth, low-latency PLB. Slower peripheral cores connect to the OPB, which reduces traffic on the PLB, resulting in greater overall system performance.

For more information, refer to:
http://www-3.ibm.com/chips/techlib/techlib.nfs/productfamilies/CoreConnect_Bus_Architecture/

Functional Description: Embedded PowerPC 405 Core

This section offers a brief overview of the various functional blocks shown in Figure 16.

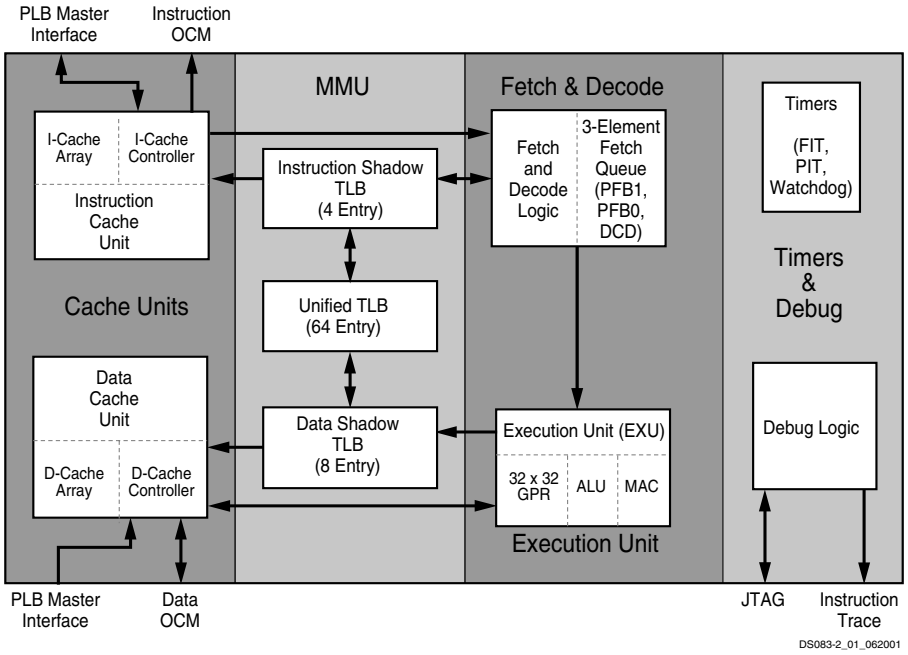

Figure 16: **Embedded PPC405 Core Block Diagram**

Embedded PPC405 Core

The embedded PPC405 core is a 32-bit Harvard architecture processor. Figure 16 illustrates its functional blocks:

- Cache units
- Memory Management unit
- Fetch Decode unit

memory protection. Working with appropriate system-level software, the MMU provides the following functions:

- Translation of the 4 GB effective address space into physical addresses
- Independent enabling of instruction and data translation/protection
- Page-level access control using the translation mechanism
- Software control of page replacement strategy
- Additional control over protection using zones
- Storage attributes for cache policy and speculative memory access control

The MMU can be disabled under software control. If the MMU is not used, the PPC405 core provides other storage control mechanisms.

Translation Look-Aside Buffer (TLB)

The Translation Look-Aside Buffer (TLB) is the hardware resource that controls translation and protection. It consists of 64 entries, each specifying a page to be translated. The TLB is fully associative; a given page entry can be placed anywhere in the TLB. The translation function of the MMU occurs pre-cache. Cache tags and indexing use physical addresses.

Software manages the establishment and replacement of TLB entries. This gives system software significant flexibility in implementing a custom page replacement strategy. For example, to reduce TLB thrashing or translation delays, software can reserve several TLB entries in the TLB for globally accessible static mappings. The instruction set provides several instructions used to manage TLB entries. These instructions are privileged and require the software to be executing in supervisor state. Additional TLB instructions are provided to move TLB entry fields to and from GPRs.

The MMU divides logical storage into pages. Eight page sizes (1 KB, 4 KB, 16 KB, 64 KB, 256 KB, 1 MB, 4 MB, and 16 MB) are simultaneously supported, such that, at any given time, the TLB can contain entries for any combination of page sizes. In order for a logical to physical translation to exist, a valid entry for the page containing the logical address must be in the TLB. Addresses for which no TLB entry exists cause TLB-Miss exceptions.

To improve performance, four instruction-side and eight data-side TLB entries are kept in shadow arrays. The shadow arrays allow single-cycle address translation and also help to avoid TLB contention between load/store and instruction fetch operations. Hardware manages the replacement and invalidation of shadow-TLB entries; no system software action is required.

Memory Protection

When address translation is enabled, the translation mechanism provides a basic level of protection.

The Zone Protection Register (ZPR) enables the system software to override the TLB access controls. For example, the ZPR provides a way to deny read access to application programs. The ZPR can be used to classify storage by type; access by type can be changed without manipulating individual TLB entries.

The PowerPC Architecture provides WIU0GE (write-back / write-through, cacheability, user-defined 0, guarded, endian) storage attributes that control memory accesses, using bits in the TLB or, when address translation is disabled, storage attribute control registers.

When address translation is enabled, storage attribute control bits in the TLB control the storage attributes associated with the current page. When address translation is disabled, bits in each storage attribute control register control the storage attributes associated with storage regions. Each storage attribute control register contains 32 fields. Each field sets the associated storage attribute for a 128 MB memory region.

Timers

The embedded PPC405 core contains a 64-bit time base and three timers, as shown in Figure 17:

- Programmable Interval Timer (PIT)
- Fixed Interval Timer (FIT)
- Watchdog Timer (WDT)

The time base counter increments either by an internal signal equal to the CPU clock rate or by a separate external timer clock signal. No interrupts are generated when the time base rolls over. The three timers are synchronous with the time base.

The PIT is a 32-bit register that decrements at the same rate as the time base is incremented. The user loads the PIT register with a value to create the desired delay. When the register reaches zero, the timer stops decrementing and generates a PIT interrupt. Optionally, the PIT can be programmed to auto-reload the last value written to the PIT register, after which the PIT continues to decrement.

The FIT generates periodic interrupts based on one of four selectable bits in the time base. When the selected bit changes from 0 to 1, the PPC405 core generates a FIT interrupt.

The WDT provides a periodic critical-class interrupt based on a selected bit in the time base. This interrupt can be used for system error recovery in the event of software or system lockups. Users may select one of four time periods for the interval and the type of reset generated if the WDT expires twice without an intervening clear from software. If enabled, the watchdog timer generates a reset unless an exception handler updates the WDT status bit before the timer has completed two of the selected timer intervals.

Table 12: **Summary of Voltage Supply Requirements for All Input and Output Standards**

I/O Standard	V_{CCO}		V_{REF}	Termination Type	
	Output	Input	Input	Output	Input
LVTTL(1)	3.3	3.3	N/R	N/R	N/R
LVCMOS33(1)			N/R	N/R	N/R
LVDCI_33(1)			N/R	Series	N/R
PCIX(2)			N/R	N/R	N/R
PCI33_3(2)			N/R	N/R	N/R
PCI66_3(2)			N/R	N/R	N/R
LVDS_25	2.5	Note (3)	N/R	N/R	N/R
LVDSEXT_25			N/R	N/R	N/R
LDT_25			N/R	N/R	N/R
ULVDS_25			N/R	N/R	N/R
BLVDS_25			N/R	N/R	N/R
LVPECL_25			N/R	N/R	N/R
SSTL2_I			1.25	N/R	N/R
SSTL2_II			1.25	N/R	N/R
LVCMOS25		2.5	N/R	N/R	N/R
LVDCI_25			N/R	Series	N/R
LVDCI_DV2_25			N/R	Series	N/R
LVDS_25_DCI			N/R	N/R	Split
LVDSEXT_25_DCI			N/R	N/R	Split
SSTL2_I_DCI			1.25	N/R	Split
SSTL2_II_DCI			1.25	Split	Split
LVDS_25_DT			N/R	N/R	N/R
LVDSEXT_25_DT			N/R	N/R	N/R
LDT_25_DT			N/R	N/R	N/R
ULVDS_25_DT			N/R	N/R	N/R

Table 12: **Summary of Voltage Supply Requirements for All Input and Output Standards *(Continued)***

I/O Standard	V_{CCO}		V_{REF}	Termination Type	
	Output	Input	Input	Output	Input
HSTL_III_18	1.8	Note (3)	1.1	N/R	N/R
HSTL_IV_18			1.1	N/R	N/R
HSTL_I_18			0.9	N/R	N/R
HSTL_II_18			0.9	N/R	N/R
SSTL18_I			0.9	N/R	N/R
SSTL18_II			0.9	N/R	N/R
LVCMOS18		1.8	N/R	N/R	N/R
LVDCI_18			N/R	Series	N/R
LVDCI_DV2_18			N/R	Series	N/R
HSTL_III_DCI_18			1.1	N/R	Single
HSTL_IV_DCI_18			1.1	Single	Single
HSTL_I_DCI_18			0.9	N/R	Split
HSTL_II_DCI_18			0.9	Split	Split
SSTL18_I_DCI			0.9	N/R	Split
SSTL18_II_DCI			0.9	Split	Split
HSTL_III	1.5	Note (3)	0.9	N/R	N/R
HSTL_IV			0.9	N/R	N/R
HSTL_I			0.75	N/R	N/R
HSTL_II			0.75	N/R	N/R
LVCMOS15		1.5	N/R	N/R	N/R
LVDCI_15			N/R	Series	N/R
LVDCI_DV2_15			N/R	Series	N/R
GTLP_DCI			1	Single	Single
HSTL_III_DCI			0.9	N/R	Single
HSTL_IV_DCI			0.9	Single	Single
HSTL_I_DCI			0.75	N/R	Split
HSTL_II_DCI			0.75	Split	Split
GTL_DCI	1.2	1.2	0.8	Single	Single
GTLP	N/R	Note (3)	1	N/R	N/R
GTL			0.8	N/R	N/R

Notes:
1. See application note **XAPP659** for more detailed information.
2. See application note **XAPP653** for more detailed information.
3. Pin voltage must not exceed V_{CCO}.
4. N/R = no requirement.

Figure 30 provides examples illustrating the use of the LVDS_25_DCI and LVDSEXT_25_DCI I/O standards. For a complete list, see the ***Virtex-II Pro Platform FPGA User Guide***.

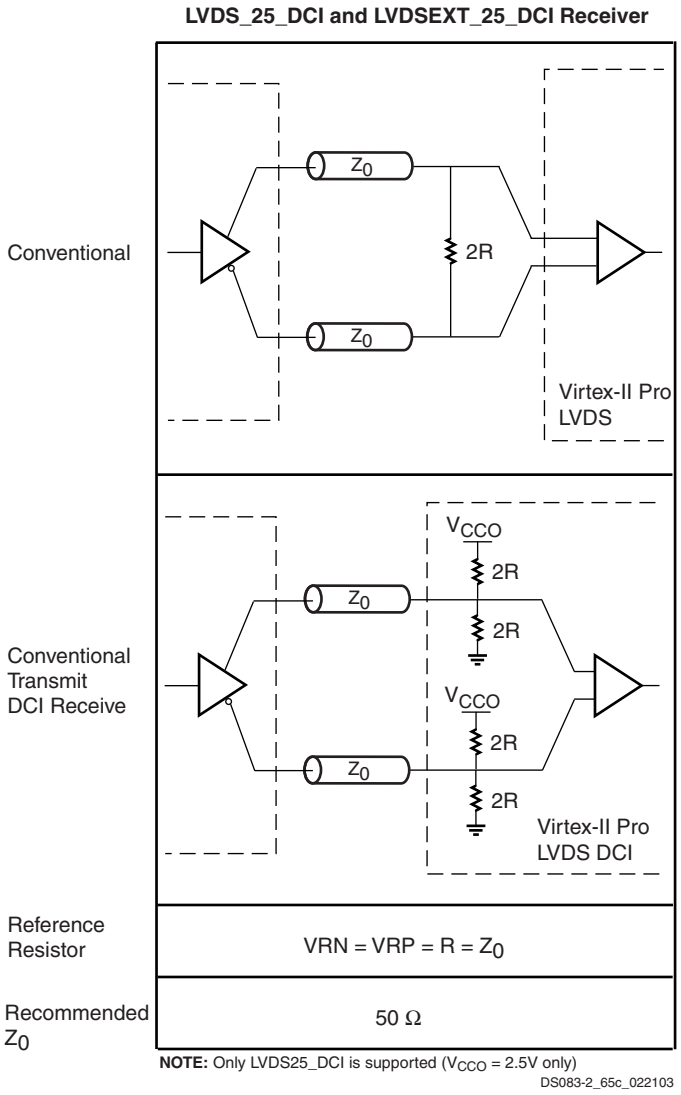

Figure 30: **LVDS DCI Usage Examples**

On-Chip Differential Termination

Virtex-II Pro provides a true 100Ω differential termination (DT) across the input differential receiver terminals. The LVDS_25_DT, LVDSEXT_25_DT, LDT_25_DT, and ULVDS_25_DT standards support on-chip differential termination.

The on-chip input differential termination in Virtex-II Pro provides major advantages over the external resistor or the DCI termination solution:

- Eliminates the stub at the receiver completely and therefore greatly improve signal integrity
- Consumes less power than DCI termination
- Supports LDT (not supported by DCI termination)
- Frees up VRP/VRN pins

Figure 31 provides examples illustrating the use of the LVDS_25_DT, LVDSEXT_25_DT, LDT_25_DT, and ULVDS_25_DT I/O standards. For further details, refer to **Solution Record 17244**. Also see the ***Virtex-II Pro Platform FPGA User Guide*** for more design information.

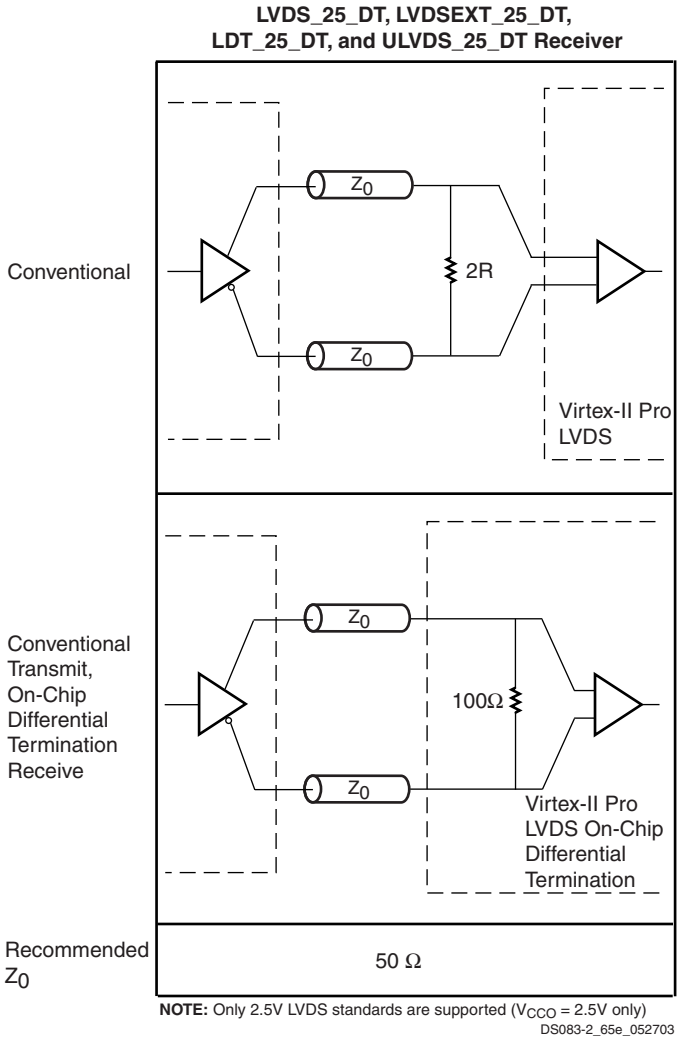

Figure 31: **LVDS Differential Termination Usage Examples**

Date	Version	Revision
03/24/03	2.5.1	• Table 10: Corrected I/O standard names SSTL18_I and SSTL18_II to SSTL18_I_DCI and SSTL18_II_DCI respectively. • Figure 61, text below: Corrected wording of criteria for clock switching.
05/27/03	2.6	• Removed Compatible Output Standards and Compatible Input Standards tables. • Added new Table 12, Summary of Voltage Supply Requirements for All Input and Output Standards. This table replaces deleted I/O standards tables. • Corrected sentence in section Input/Output Individual Options, page 27, to read “The optional weak-keeper circuit is connected to each *user I/O pad*.” • Added section Rules for Combining I/O Standards in the Same Bank, page 29.
06/02/03	2.7	• Added four Differential Termination I/O standards to Table 9 and Table 12. • Added section On-Chip Differential Termination and Figure 31, page 34.
08/25/03	2.7.1	• Added footnote referring to XAPP659 to 3.3V I/O callouts in Table 8 and Table 12.
09/10/03	2.8	• Section Configuration, page 56: Added text indicating that the mode pins M0-M2 must be held to a constant DC level during and after configuration.
10/14/03	2.9	• Deleted section Functional Description: RocketIO Multi-Gigabit Transceiver (MGT), page 10. Added section Local Clocking, page 51. • Sections Slave-Serial Mode and Master-Serial Mode, page 56: Changed "rising" to "falling" edge with respect to DOUT. • Table 8, page 24 and Table 10, page 25: Corrected Input V_{REF} for HSTL_III-IV_18 from 1.08V to 1.1V.
12/10/03	3.0	• XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, are released to **Production status**.
02/19/04	3.1	• Section BUFGMUX, page 50: Corrected the definition of the "presently selected clock" to be I0 or I1. Corrected signal names in Figure 61 and associated text from CLK0 and CLK1 to I0 and I1.
03/09/04	3.1.1	• Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
04/22/04	3.2	• Section Clock De-skew, page 52: Removed reference to CLK2X as an option for DCM clock feedback.
06/30/04	4.0	Merged in DS110-2 (Module 2 of Virtex-II Pro X data sheet). Separate RocketIO and RocketIO X sections created.
11/17/04	4.1	• Figure 11, page 12: Corrected figure by removing coupling capacitors from input. • Section Rules for Combining I/O Standards in the Same Bank, page 29: Corrected I/O standard in the first example from LVDS_25_DCI to LVDS_25.
03/01/05	4.2	• Reassigned heading hierarchies for better agreement with content. • Table 7: Corrected VCCAUXTX and VCCAUXRX to AVCCAUXTX and AVCCAUXRX respectively. • Table 9: Corrected V_{OD} (output voltage) range for LVDSEXT_25. • Table 25: Corrected SelectRAM+ memory available for XC2VPX70 device. • Table 33: Updated configuration default bitstream lengths.
06/20/05	4.3	*No changes in Module 2 for this revision.*
09/15/05	4.4	• Table 1: Deleted SONET OC-192 protocol. • Table 3: Deleted RocketIO X primitives for SONET OC-192, 10 Gbit Ethernet, and Xilinx 10G (Aurora) protocols. • Changed all instances of 10.3125 Gb/s to 6.25 Gb/s. • Table 7: Changed RocketIO X VCCAUXRX from 1.5V globally to 1.5V for 8B/10B encoding, 1.8V for all other encoding protocols.

Table 17: **Processor Block Switching Characteristics**

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
Setup and Hold Relative to Clock (CPMC405CLOCK)					
Device Control Register Bus control inputs	$T_{PCCK\_}DCR/T_{PCKC\_}DCR$	0.38/–0.18	0.44/–0.20	0.48/–0.23	ns, min
Device Control Register Bus data inputs	$T_{PDCK\_}DCR/T_{PCKD\_}DCR$	0.65/–0.01	0.75/–0.01	0.82/–0.02	ns, min
Clock and Power Management control inputs	$T_{PCCK\_}CPM/T_{PCKC\_}CPM$	0.16/ 0.03	0.19/ 0.03	0.20/ 0.03	ns, min
Reset control inputs	$T_{PCCK\_}RST/T_{PCKC\_}RST$	0.16/ 0.03	0.19/ 0.03	0.20/ 0.03	ns, min
Debug control inputs	$T_{PCCK\_}DBG/T_{PCKC\_}DBG$	0.27/ 0.30	0.31/ 0.35	0.34/ 0.38	ns, min
Trace control inputs	$T_{PCCK\_}TRC/T_{PCKC\_}TRC$	1.37/–0.41	1.57/–0.48	1.73/–0.52	ns, min
External Interrupt Controller control inputs	$T_{PCCK\_}EIC/T_{PCKC\_}EIC$	0.57/–0.22	0.66/–0.25	0.72/–0.27	ns, min
Clock to Out					
Device Control Register Bus control outputs	$T_{PCKCO\_}DCR$	1.32	1.52	1.67	ns, max
Device Control Register Bus address outputs	$T_{PCKAO\_}DCR$	1.72	1.98	2.17	ns, max
Device Control Register Bus data outputs	$T_{PCKDO\_}DCR$	1.76	2.02	2.22	ns, max
Clock and Power Management control outputs	$T_{PCKCO\_}CPM$	1.26	1.45	1.59	ns, max
Reset control outputs	$T_{PCKCO\_}RST$	1.32	1.51	1.66	ns, max
Debug control outputs	$T_{PCKCO\_}DBG$	1.94	2.22	2.44	ns, max
Trace control outputs	$T_{PCKCO\_}TRC$	1.35	1.56	1.71	ns, max
Clock					
CPMC405CLOCK minimum pulse width, high	T_{CPWH}	1.25	1.42	1.66	ns, min
CPMC405CLOCK minimum pulse width, low	T_{CPWL}	1.25	1.42	1.66	ns, min

Table 18: **Processor Block PLB Switching Characteristics**

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
Setup and Hold Relative to Clock (PLBCLK)					
Processor Local Bus(ICU/DCU) control inputs	$T_{PCCK\_}PLB/T_{PCKC\_}PLB$	0.98/ 0.18	1.12/ 0.21	1.23/ 0.23	ns, min
Processor Local Bus (ICU/DCU) data inputs	$T_{PDCK\_}PLB/T_{PCKD\_}PLB$	0.62/ 0.16	0.71/ 0.18	0.78/ 0.20	ns, min
Clock to Out					
Processor Local Bus(ICU/DCU) control outputs	$T_{PCKCO\_}PLB$	1.34	1.54	1.69	ns, max
Processor Local Bus(ICU/DCU) address bus outputs	$T_{PCKAO\_}PLB$	1.16	1.34	1.47	ns, max
Processor Local Bus(ICU/DCU) data bus outputs	$T_{PCKDO\_}PLB$	1.44	1.65	1.81	ns, max

Table 36: **IOB Input Switching Characteristics Standard Adjustments *(Continued)***

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
HSLVDCI, 1.8V	HSLVDCI_18	$T_{IHSLVDCI\_18}$	0.59	0.68	0.75	ns
HSLVDCI, 2.5V	HSLVDCI_25	$T_{IHSLVDCI\_25}$	0.59	0.68	0.75	ns
HSLVDCI, 3.3V	HSLVDCI_33	$T_{IHSLVDCI\_33}$	0.59	0.68	0.75	ns
GTL (Gunning Transceiver Logic) with DCI	GTL_DCI	T_{IGTL_DCI}	0.49	0.57	0.62	ns
GTL Plus with DCI	GTLP_DCI	T_{IGTLP_DCI}	0.27	0.31	0.35	ns
HSTL (High-Speed Transceiver Logic), Class I, with DCI	HSTL_I_DCI	$T_{IHSTL\_I\_DCI}$	0.27	0.31	0.35	ns
HSTL, Class II, with DCI	HSTL_II_DCI	$T_{IHSTL\_II\_DCI}$	0.27	0.31	0.35	ns
HSTL, Class III, with DCI	HSTL_III_DCI	$T_{IHSTL\_III\_DCI}$	0.27	0.31	0.35	ns
HSTL, Class IV, with DCI	HSTL_IV_DCI	$T_{IHSTL\_IV\_DCI}$	0.27	0.31	0.35	ns
HSTL, Class I, 1.8V, with DCI	HSTL_I_DCI_18	$T_{IHSTL\_I\_DCI\_18}$	0.27	0.31	0.35	ns
HSTL, Class II, 1.8V, with DCI	HSTL_II_DCI_18	$T_{IHSTL\_II\_DCI\_18}$	0.27	0.31	0.35	ns
HSTL, Class III, 1.8V, with DCI	HSTL_III_DCI_18	$T_{IHSTL\_III\_DCI\_18}$	0.27	0.31	0.35	ns
HSTL, Class IV, 1.8V, with DCI	HSTL_IV_DCI_18	$T_{IHSTL\_IV\_DCI\_18}$	0.27	0.31	0.35	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V, with DCI	SSTL18_I_DCI	$T_{ISSTL18\_I\_DCI}$	0.62	0.72	0.79	ns
SSTL, Class II, 1.8V, with DCI	SSTL18_II_DCI	$T_{ISSTL18\_II\_DCI}$	0.64	0.73	0.81	ns
SSTL, Class I, 2.5V, with DCI	SSTL2_I_DCI	$T_{ISSTL2\_I\_DCI}$	0.17	0.20	0.22	ns
SSTL, Class II, 2.5V, with DCI	SSTL2_II_DCI	$T_{ISSTL2\_II\_DCI}$	0.17	0.20	0.22	ns
LVDS, 2.5V, with DCI	LVDS_25_DCI	$T_{ILVDS\_25\_DCI}$	0.31	0.36	0.40	ns
LVDSEXT, 2.5V, with DCI	LVDSEXT_25_DCI	$T_{ILVDSEXT\_25\_DCI}$	0.33	0.37	0.41	ns
LVDS, 2.5V, with Differential Termination (DT)	LVDS_25_DT	$T_{ILVDS\_25\_DT}$	0.31	0.36	0.40	ns
LVDSEXT, 2.5V, with DT	LVDSEXT_25_DT	$T_{ILVDSEXT\_25\_DT}$	0.33	0.37	0.41	ns
ULVDS, 2.5V, with DT	ULVDS_25_DT	$T_{IULVDS\_25\_DT}$	0.31	0.36	0.40	ns
LDT, 2.5V, with DT	LDT_25_DT	$T_{ILDT\_25\_DT}$	0.31	0.36	0.40	ns

IOB Output Switching Characteristics

Output delays terminating at a pad are specified for LVCMOS25 with 12 mA drive and fast slew rate. For other standards, adjust the delays with the values shown in IOB Output Switching Characteristics Standard Adjustments.

Table 37: **IOB Output Switching Characteristics**

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
Propagation Delays					
O input to Pad	T_{IOOP}	1.58	1.68	1.85	ns, max
O input to Pad via transparent latch	T_{IOOLP}	1.65	1.82	1.99	ns, max
3-State Delays					
T input to Pad high-impedance(2)	T_{IOTHZ}	1.23	1.35	1.51	ns, max
T input to valid data on Pad	T_{IOTP}	1.51	1.63	1.78	ns, max
T input to Pad high-impedance via transparent latch(2)	$T_{IOTLPHZ}$	1.08	1.22	1.36	ns, max
T input to valid data on Pad via transparent latch	$T_{IOTLPON}$	1.56	1.69	1.85	ns, max
GTS to Pad high-impedance(2)	T_{GTS}	4.11	4.73	5.20	ns, max
Sequential Delays					
Clock CLK to Pad	T_{IOCKP}	1.59	1.76	1.93	ns, max
Clock CLK to Pad high-impedance (synchronous)(2)	T_{IOCKHZ}	1.39	1.55	1.73	ns, max
Clock CLK to valid data on Pad (synchronous)	T_{IOCKON}	1.67	1.82	2.00	ns, max
Setup and Hold Times Before/After Clock CLK					
O input	T_{IOOCK}/T_{IOCKO}	0.23/ 0.12	0.26/ 0.14	0.29/ 0.15	ns, min
OCE input	$T_{IOOCECK}/T_{IOCKOCE}$	0.39/ 0.01	0.44/ 0.01	0.49/ 0.01	ns, min
SR input (OFF)	$T_{IOSRCKO}/T_{IOCKOSR}$	0.52/ 0.00	0.57/ 0.00	0.75/ 0.00	ns, min
3–State Setup Times, T input	T_{IOTCK}/T_{IOCKT}	0.23/ 0.12	0.26/ 0.14	0.29/ 0.15	ns, min
3-State Setup Times, TCE input	$T_{IOTCECK}/T_{IOCKTCE}$	0.39/ 0.01	0.44/ 0.01	0.49/ 0.01	ns, min
3-State Setup Times, SR input (TFF)	$T_{IOSRCKT}/T_{IOCKTSR}$	0.52/ 0.00	0.57/ 0.00	0.75/ 0.00	ns, min
Set/Reset Delays					
Minimum Pulse Width, SR inputs (asynchronous)	T_{RPW}	0.37	0.40	0.45	ns, min
SR input to Pad (asynchronous)	T_{IOSRP}	2.33	2.56	2.83	ns, max
SR input to Pad high-impedance (asynchronous)(2)	T_{IOSRHZ}	1.97	2.16	2.41	ns, max
SR input to valid data on Pad (asynchronous)	T_{IOSRON}	2.24	2.44	2.69	ns, max
GSR to Pad	T_{IOGSRQ}	5.87	6.75	7.43	ns, max

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.
2. The 3-state turn-off delays should not be adjusted.

Table 5: **FG256/FGG256 — XC2VP2 and XC2VP4**

Bank	Pin Description	Pin Number
N/A	AVCCAUXRX7	B13
N/A	AVCCAUXRX18	R13
N/A	VTRXPAD18	R12
N/A	RXNPAD18	T13
N/A	RXPPAD18	T12
N/A	GNDA18	P11
N/A	TXPPAD18	T11
N/A	TXNPAD18	T10
N/A	VTTXPAD18	R10
N/A	AVCCAUXTX18	R11
N/A	AVCCAUXRX19	R7
N/A	VTRXPAD19	R6
N/A	RXNPAD19	T7
N/A	RXPPAD19	T6
N/A	GNDA19	P6
N/A	TXPPAD19	T5
N/A	TXNPAD19	T4
N/A	VTTXPAD19	R4
N/A	AVCCAUXTX19	R5
N/A	VCCINT	N4
N/A	VCCINT	N13
N/A	VCCINT	M5
N/A	VCCINT	M12
N/A	VCCINT	E5
N/A	VCCINT	E12
N/A	VCCINT	D4
N/A	VCCINT	D13
N/A	VCCAUX	R16
N/A	VCCAUX	R1
N/A	VCCAUX	B16
N/A	VCCAUX	B1
N/A	GND	T16
N/A	GND	T1
N/A	GND	R2

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	GND		C14			
N/A	GND		C3			
N/A	GND		B29			
N/A	GND		B2			
N/A	GND		A22			
N/A	GND		A9			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
N/A	VCCINT	Y13				
N/A	VCCINT	Y22				
N/A	VCCINT	AA13				
N/A	VCCINT	AA22				
N/A	VCCINT	AB13				
N/A	VCCINT	AB14				
N/A	VCCINT	AB15				
N/A	VCCINT	AB16				
N/A	VCCINT	AB17				
N/A	VCCINT	AB18				
N/A	VCCINT	AB19				
N/A	VCCINT	AB20				
N/A	VCCINT	AB21				
N/A	VCCINT	AB22				
N/A	VCCINT	AC12				
N/A	VCCINT	AC23				
N/A	VCCINT	AD11				
N/A	VCCINT	AD24				
N/A	VCCAUX	C3				
N/A	VCCAUX	C4				
N/A	VCCAUX	C17				
N/A	VCCAUX	C18				
N/A	VCCAUX	C31				
N/A	VCCAUX	C32				
N/A	VCCAUX	D3				
N/A	VCCAUX	D32				
N/A	VCCAUX	U1				
N/A	VCCAUX	V1				
N/A	VCCAUX	U34				
N/A	VCCAUX	V34				
N/A	VCCAUX	AL3				
N/A	VCCAUX	AL32				
N/A	VCCAUX	AM3				
N/A	VCCAUX	AM4				
N/A	VCCAUX	AM17				
N/A	VCCAUX	AM18				
N/A	VCCAUX	AM31				
N/A	VCCAUX	AM32				

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L02P_2	D9		
2	IO_L03N_2	B7		
2	IO_L03P_2	A7		
2	IO_L04N_2/VREF_2	B6		
2	IO_L04P_2	A6		
2	IO_L05N_2	E8		
2	IO_L05P_2	D8		
2	IO_L06N_2	B4		
2	IO_L06P_2	A4		
2	IO_L07N_2	B3		
2	IO_L07P_2	A3		
2	IO_L08N_2	H7		
2	IO_L08P_2	H8		
2	IO_L09N_2	C6		
2	IO_L09P_2	C7		
2	IO_L10N_2/VREF_2	C5		
2	IO_L10P_2	B5		
2	IO_L11N_2	K8		
2	IO_L11P_2	J8		
2	IO_L12N_2	C1		
2	IO_L12P_2	C2		
2	IO_L13N_2	E7		
2	IO_L13P_2	D7		
2	IO_L14N_2	J6		
2	IO_L14P_2	J7		
2	IO_L15N_2	D5		
2	IO_L15P_2	D6		
2	IO_L16N_2/VREF_2	E4		
2	IO_L16P_2	D4		
2	IO_L17N_2	L9		
2	IO_L17P_2	K9		
2	IO_L18N_2	E3		
2	IO_L18P_2	D3		
2	IO_L19N_2	D1		
2	IO_L19P_2	D2		
2	IO_L20N_2	K7		
2	IO_L20P_2	L7		
2	IO_L21N_2	F6		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
6	IO_L44N_6	AA28		
6	IO_L45P_6	AC31		
6	IO_L45N_6/VREF_6	AC32		
6	IO_L46P_6	AC29		
6	IO_L46N_6	AC30		
6	IO_L47P_6	AA24		
6	IO_L47N_6	AA25		
6	IO_L48P_6	AB32		
6	IO_L48N_6	AB33		
6	IO_L49P_6	AB28		
6	IO_L49N_6	AB29		
6	IO_L50P_6	AA26		
6	IO_L50N_6	Y26		
6	IO_L51P_6	AA33		
6	IO_L51N_6/VREF_6	AA34		
6	IO_L52P_6	AB31		
6	IO_L52N_6	AA31		
6	IO_L53P_6	Y24		
6	IO_L53N_6	Y25		
6	IO_L54P_6	AA29		
6	IO_L54N_6	AA30		
6	IO_L55P_6	Y33		
6	IO_L55N_6	Y34		
6	IO_L56P_6	Y28		
6	IO_L56N_6	W27		
6	IO_L57P_6	AA32		
6	IO_L57N_6/VREF_6	Y32		
6	IO_L58P_6	Y29		
6	IO_L58N_6	Y30		
6	IO_L59P_6	W24		
6	IO_L59N_6	W25		
6	IO_L60P_6	W31		
6	IO_L60N_6	W32		
6	IO_L85P_6	W28		
6	IO_L85N_6	W29		
6	IO_L86P_6	V26		
6	IO_L86N_6	V27		
6	IO_L87P_6	W33		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	IO_L30N_2	N6		
2	IO_L30P_2	N7		
2	IO_L31N_2	M4		
2	IO_L31P_2	N5		
2	IO_L32N_2	R11		
2	IO_L32P_2	R12		
2	IO_L33N_2	N1		
2	IO_L33P_2	N2		
2	IO_L34N_2/VREF_2	P6		
2	IO_L34P_2	P7		
2	IO_L35N_2	R13		
2	IO_L35P_2	T13		
2	IO_L36N_2	P4		
2	IO_L36P_2	P5		
2	IO_L37N_2	P3		
2	IO_L37P_2	N3		
2	IO_L38N_2	T10		
2	IO_L38P_2	T11		
2	IO_L39N_2	P1		
2	IO_L39P_2	P2		
2	IO_L40N_2/VREF_2	R7		
2	IO_L40P_2	R8		
2	IO_L41N_2	T12		
2	IO_L41P_2	U12		
2	IO_L42N_2	R5		
2	IO_L42P_2	R6		
2	IO_L43N_2	R3		
2	IO_L43P_2	R4		
2	IO_L44N_2	U8		
2	IO_L44P_2	T8		
2	IO_L45N_2	R1		
2	IO_L45P_2	R2		
2	IO_L46N_2/VREF_2	T6		
2	IO_L46P_2	T7		
2	IO_L47N_2	U9		
2	IO_L47P_2	U10		
2	IO_L48N_2	T2		
2	IO_L48P_2	T3		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
6	IO_L15P_6	AL37		
6	IO_L15N_6/VREF_6	AK37		
6	IO_L16P_6	AL33		
6	IO_L16N_6	AL34		
6	IO_L17P_6	AH32		
6	IO_L17N_6	AG31		
6	IO_L18P_6	AK38		
6	IO_L18N_6	AK39		
6	IO_L19P_6	AK35		
6	IO_L19N_6	AK36		
6	IO_L20P_6	AF28		
6	IO_L20N_6	AF29		
6	IO_L21P_6	AK33		
6	IO_L21N_6/VREF_6	AK34		
6	IO_L22P_6	AJ38		
6	IO_L22N_6	AJ39		
6	IO_L23P_6	AG30		
6	IO_L23N_6	AF30		
6	IO_L24P_6	AJ36		
6	IO_L24N_6	AJ37		
6	IO_L25P_6	AJ34		
6	IO_L25N_6	AJ35		
6	IO_L26P_6	AF31		
6	IO_L26N_6	AF32		
6	IO_L27P_6	AJ32		
6	IO_L27N_6/VREF_6	AJ33		
6	IO_L28P_6	AH37		
6	IO_L28N_6	AH38		
6	IO_L29P_6	AE27		
6	IO_L29N_6	AD27		
6	IO_L30P_6	AH36		
6	IO_L30N_6	AG35		
6	IO_L31P_6	AH33		
6	IO_L31N_6	AH34		
6	IO_L32P_6	AE28		
6	IO_L32N_6	AE29		
6	IO_L33P_6	AG38		
6	IO_L33N_6/VREF_6	AG39		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND	AU3		
N/A	GND	AT3		
N/A	GND	D3		
N/A	GND	C3		
N/A	GND	B3		
N/A	GND	AN12		
N/A	GND	G12		
N/A	GND	C12		
N/A	GND	Y10		
N/A	GND	AH9		
N/A	GND	AD9		
N/A	GND	T9		
N/A	GND	M9		
N/A	GND	AU8		
N/A	GND	AN8		
N/A	GND	G8		
N/A	GND	C8		
N/A	GND	Y6		
N/A	GND	AM5		
N/A	GND	AH5		
N/A	GND	T17		
N/A	GND	AT16		
N/A	GND	AN16		
N/A	GND	AJ16		
N/A	GND	AC16		
N/A	GND	AB16		
N/A	GND	AA16		
N/A	GND	Y16		
N/A	GND	W16		
N/A	GND	V16		
N/A	GND	U16		
N/A	GND	L16		
N/A	GND	G16		
N/A	GND	D16		
N/A	GND	AU12		
N/A	GND	AB18		
N/A	GND	AA18		
N/A	GND	Y18		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND	AM39		
N/A	GND	AH39		
N/A	GND	AD39		
N/A	GND	T39		
N/A	GND	M39		
N/A	GND	H39		
N/A	GND	C39		
N/A	GND	AV38		
N/A	GND	AU38		
N/A	GND	AA38		
N/A	GND	W38		
N/A	GND	C38		

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	IO_L59N_2	AA11	
2	IO_L59P_2	AA12	
2	IO_L60N_2	W1	
2	IO_L60P_2	W2	
2	IO_L85N_2	Y2	
2	IO_L85P_2	Y3	
2	IO_L86N_2	AA9	
2	IO_L86P_2	AA10	
2	IO_L87N_2	AA5	
2	IO_L87P_2	AA6	
2	IO_L88N_2/VREF_2	AA4	
2	IO_L88P_2	Y4	
2	IO_L89N_2	AA7	
2	IO_L89P_2	AA8	
2	IO_L90N_2	AA2	
2	IO_L90P_2	AA3	
3	IO_L90N_3	AB5	
3	IO_L90P_3	AB6	
3	IO_L89N_3	AB11	
3	IO_L89P_3	AB12	
3	IO_L88N_3	AB2	
3	IO_L88P_3	AB3	
3	IO_L87N_3/VREF_3	AB4	
3	IO_L87P_3	AC4	
3	IO_L86N_3	AB9	
3	IO_L86P_3	AB10	
3	IO_L85N_3	AC2	
3	IO_L85P_3	AC3	
3	IO_L60N_3	AD5	
3	IO_L60P_3	AD6	
3	IO_L59N_3	AB7	
3	IO_L59P_3	AB8	
3	IO_L58N_3	AD1	
3	IO_L58P_3	AD2	
3	IO_L57N_3/VREF_3	AE4	
3	IO_L57P_3	AE5	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L33N_6/VREF_6	AK40	
6	IO_L34P_6	AK36	
6	IO_L34N_6	AK37	
6	IO_L35P_6	AE36	
6	IO_L35N_6	AE37	
6	IO_L36P_6	AJ41	
6	IO_L36N_6	AJ42	
6	IO_L37P_6	AJ40	
6	IO_L37N_6	AH40	
6	IO_L38P_6	AE34	
6	IO_L38N_6	AE35	
6	IO_L39P_6	AJ38	
6	IO_L39N_6/VREF_6	AH37	
6	IO_L40P_6	AJ36	
6	IO_L40N_6	AJ37	
6	IO_L41P_6	AE32	
6	IO_L41N_6	AE33	
6	IO_L42P_6	AH41	
6	IO_L42N_6	AH42	
6	IO_L43P_6	AH38	
6	IO_L43N_6	AH39	
6	IO_L44P_6	AD36	
6	IO_L44N_6	AC35	
6	IO_L45P_6	AH36	
6	IO_L45N_6/VREF_6	AG36	
6	IO_L46P_6	AG41	
6	IO_L46N_6	AG42	
6	IO_L47P_6	AD34	
6	IO_L47N_6	AC33	
6	IO_L48P_6	AG40	
6	IO_L48N_6	AF39	
6	IO_L49P_6	AG38	
6	IO_L49N_6	AG39	
6	IO_L50P_6	AD32	
6	IO_L50N_6	AD33	
6	IO_L51P_6	AG37	
6	IO_L51N_6/VREF_6	AF37	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	VCCINT	W16	
N/A	VCCINT	V16	
N/A	VCCINT	U16	
N/A	VCCINT	T16	
N/A	VCCINT	R16	
N/A	VCCINT	P16	
N/A	VCCINT	AJ15	
N/A	VCCINT	AH15	
N/A	VCCINT	R15	
N/A	VCCINT	P15	
N/A	VCCINT	AJ14	
N/A	VCCINT	P14	
N/A	VCCINT	AK13	
N/A	VCCINT	N13	
N/A	VCCAUX	BA42	
N/A	VCCAUX	AY42	
N/A	VCCAUX	AL42	
N/A	VCCAUX	AB42	
N/A	VCCAUX	AA42	
N/A	VCCAUX	M42	
N/A	VCCAUX	C42	
N/A	VCCAUX	B42	
N/A	VCCAUX	BB41	
N/A	VCCAUX	A41	
N/A	VCCAUX	BB40	
N/A	VCCAUX	A40	
N/A	VCCAUX	BB31	
N/A	VCCAUX	A31	
N/A	VCCAUX	BB22	
N/A	VCCAUX	A22	
N/A	VCCAUX	BB21	
N/A	VCCAUX	A21	
N/A	VCCAUX	BB12	
N/A	VCCAUX	A12	
N/A	VCCAUX	BB3	
N/A	VCCAUX	A3	
N/A	VCCAUX	BB2	